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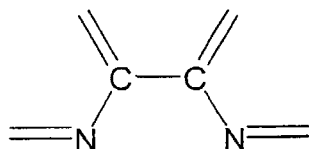
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(54) Title: ACIDIC SOLUTION FOR SILVER DEPOSITION AND METHOD FOR SILVER LAYER DEPOSITION ON METAL SURFACES



(I)

(57) Abstract: A processing solution and a method are used for producing solderable and bondable silver layers the properties of which are not degraded even after storing, with no anti-tarnishing compounds being utilized as contrasted with prior art solutions and methods. The acidic solution for silver deposition contains silver ions and at least one Cu(I) complexing agent, said Cu(I) complexing agent being selected from the group comprising compounds having the structural element (I).



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